

## CLAIM(S):

1. A slider supporting a transducing head proximate a rotating disc, the slider positioned on a gimbal having a slider opposing face with a flex circuit material on the slider opposing face and a flex on suspension (FOS) bond pad located on the flex circuit material, the slider comprising:
  - a slider body having a leading edge and a trailing edge, a forward face adjacent the trailing edge, and at least one slider bond pad located on the forward face; and
  - means for positioning the slider on the flex circuit material of the gimbal such that the slider bond pad is aligned with the FOS bond pad.
2. The slider of claim 1 wherein the means for positioning the slider on the flex circuit material comprises:
  - an extended bond pad on the forward face such that the extended bond pad is aligned with the FOS bond pad; and
  - a notch located along the forward face adjacent a gimbal opposing face of the slider wherein the notch and the extended bond pad provide a tolerance buffer.
3. The slider of claim 2 wherein the extended bond pad further comprises:
  - a copper stud formed on the forward face;
  - a pad extension plated upon the forward face; and
  - a gold bond pad mounted to the pad extension.
4. A method for aligning a slider on a gimbal wherein the gimbal includes a slider opposing face, the gimbal has a flex circuit material disposed on

the slider opposing face and a flex on suspension (FOS) bond pad is disposed on the flex circuit material, the method comprising:

providing a slider having a gimbal opposing face and a disc opposing face bounded by a leading edge and a trailing edge, the slider having a forward face along the trailing edge extending between the gimbal opposing face and the disc opposing face;

forming an extended bond pad on the forward face of the slider;

forming a notch on the slider in the forward face adjacent the gimbal opposing face wherein the notch and the extended bond pad provide a tolerance buffer; and

placing the slider on the flex circuit material such that the extended bond pad is positioned relative the FOS bond pad to improve bond strength and static attitude.

5. The method of claim 4, and further comprising:

mounting the gimbal on the actuation assembly such that the slider is centered on a dimple formed on a load beam of the actuation assembly.

6. The method of claim 4 wherein forming the extended bond pad comprises:

forming a copper stud on the forward face of the slider body;

sputtering a first seedlayer on top of the copper stud and the forward face;

patterning a pad extension photoresist mask upon the first seedlayer;

plating nickel iron in the pad extension photoresist mask to form a pad extension;  
stripping the pad extension photoresist mask;  
sputtering a second seedlayer upon the pad extension; and  
mounting a gold bond pad to the pad extension.

7. The method of claim 4 wherein forming the notch comprises slicing a portion of the forward face from the slider with a grinding wheel.
8. The method of claim 4 wherein forming the notch comprises cutting small strips along the gimbal opposing face of the slider using a laser.
9. The method of claim 4 wherein forming the notch comprises etching with a wafer etch process.
10. The method of claim 4 wherein the notch has a depth with respect to the forward face of about 40 microns.
11. The method of claim 4 wherein the notch has a height with respect to the gimbal opposing face of about 25 microns.
12. The method of claim 4 wherein the extended bond pad has a thickness between about 5 microns and about 15 microns.
13. The method of claim 4 wherein the extended bond pad is perpendicularly aligned with the FOS bond pad and there is a gap between the extended bond pad and the FOS bond pad.

14. The method of claim 4 wherein attaching the slider to the flex circuit further comprises ball bonding.

15. A slider supporting a transducing head proximate a rotating disc, the slider positioned on a gimbal having a slider opposing face coated with a flex circuit material and at least one flex on suspension (FOS) bond pad located on the flex circuit material, the slider comprising:

a slider body having a gimbal opposing face and a disc opposing face;

a forward face extending between the gimbal opposing face and the disc opposing face;

an extended bond pad located on the forward face such that the extended bond pad is aligned with the FOS bond pad; and

a notch located along the forward face adjacent the gimbal opposing face wherein the notch and the extended bond pad provide a tolerance buffer for aligning the extended bond pad to the FOS bond pad.

16. The slider of claim 15 wherein a gold bond pad is mounted to the extended bond pad.

17. The slider of claim 15 wherein the extended bond pad further comprises:

a copper stud formed on the forward face;

a pad extension plated upon the forward face; and

a gold bond pad mounted to the pad extension.

18. The slider of claim 15 further comprising a ball bond between the extended bond pad and its respective FOS bond pad.
19. The slider of claim 15 wherein there is a gap between the extended bond pad and the FOS bond pad.
20. The slider of claim 15 wherein the notch is formed by slicing a portion of the forward face with a grinding wheel.
21. The slider of claim 15 wherein the notch is formed by cutting small strips along the gimbal opposing face using a laser.
22. The slider of claim 15 wherein the notch is formed using a wafer etch process.